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Understanding [Embedded - Microprocessors](#)

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of [Embedded - Microprocessors](#)

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details

Product Status	Obsolete
Core Processor	ARM7TDMI
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	74MHz
Co-Processors/DSP	-
RAM Controllers	SDRAM
Graphics Acceleration	No
Display & Interface Controllers	Keypad, LCD, Touchscreen
Ethernet	-
SATA	-
USB	-
Voltage - I/O	2.5V, 2.7V, 3.0V, 3.3V
Operating Temperature	-40°C ~ 85°C (TA)
Security Features	Hardware ID
Package / Case	208-LQFP
Supplier Device Package	208-LQFP
Purchase URL	https://www.e-xfl.com/product-detail/cirrus-logic/ep7312-iv

FEATURES (cont)

- 48 KBytes of on-chip SRAM
- MaverickKey™ IDs
 - 32-bit unique ID can be used for DRM compliance
 - 128-bit random ID
- Available in 74 and 90 MHz clock speeds
- LCD controller
 - Interfaces directly to a single-scan panel monochrome STN LCD
 - Interfaces to a single-scan panel color STN LCD with minimal external glue logic
- Full JTAG boundary scan and Embedded ICE® support
- Integrated Peripheral Interfaces
 - 32-bit SDRAM Interface up to 2 external banks
 - 8/32/16-bit SRAM/FLASH/ROM Interface
 - Digital Audio Interface providing glueless interface to low-power DACs, ADCs and CODECs
 - Two Synchronous Serial Interfaces (SSI1, SSI2)
 - CODEC Sound Interface
 - 8x8 Keypad Scanner
- 27 General Purpose Input/Output pins
- Dedicated LED flasher pin from the RTC
- Internal Peripherals
 - Two 16550 compatible UARTs
 - IrDA Interface
 - Two PWM Interfaces
 - Real-time Clock
 - Two general purpose 16-bit timers
 - Interrupt Controller
 - Boot ROM
- Package
 - 208-Pin LQFP
 - 256-Ball PBGA
 - 204-Ball TFBGA
- The fully static EP7312 is optimized for low power dissipation and is fabricated on a 0.25 micron CMOS process

OVERVIEW (cont.)

The EP7312 is designed for ultra-low-power operation. Its core operates at only 2.5 V, while its I/O has an operation range of 2.5 V–3.3 V. The device has three basic power states: operating, idle and standby.

MaverickKey unique hardware programmed IDs are a solution to the growing concern over secure web content and commerce. With Internet security playing an important role in the delivery of digital media such as books or music, traditional software methods are quickly becoming unreliable. The MaverickKey unique IDs provide OEMs with a method of utilizing specific hardware IDs such as those assigned for SDMI (Secure Digital Music Initiative) or any other authentication mechanism.

The EP7312 integrates an interface to enable a direct connection to many low cost, low power, high quality audio converters. In particular, high quality ADCs, DACs, or CODECs such as the Cirrus Logic CS53L32A, CS43L42, and CS42L50 are easily added to an EP73xx design via the DAI. Some of these devices feature digital bass and treble boost, digital volume control and compressor-limiter functions.

Simply by adding desired memory and peripherals to the highly integrated EP7312 completes a low-power system solution. All necessary interface logic is integrated on-chip.

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64-Key Keypad Interface

Matrix keyboards and keypads can be easily read by the EP7312. A dedicated 8-bit column driver output generates strobes for each keyboard column signal. The pins of Port A, when configured as inputs, can be selectively OR'ed together to provide a keyboard interrupt that is capable of waking the system from a STANDBY or IDLE state. The Keypad Interface has these features:

- Column outputs can be individually set high with the remaining bits left at high-impedance
- Column outputs can be driven all-low, all-high, or all-high-impedance
- Keyboard interrupt driven by OR'ing together all Port A bits
- Keyboard interrupt can be used to wake up the system
- 8x8 keyboard matrix usable with no external logic, extra keys can be added with minimal glue logic

Table 10 shows the Keypad Interface Pin Assignments.

Table 10. Keypad Interface Pin Assignments

Pin Mnemonic	I/O	Pin Description
COL[7:0]	O	Keyboard scanner column drive

Interrupt Controller

When unexpected events arise during the execution of a program (i.e., interrupt or memory fault) an exception is usually generated. When these exceptions occur at the same time, a fixed priority system determines the order in which they are handled. The EP7312 interrupt controller has two interrupt types: interrupt request (IRQ) and fast interrupt request (FIQ). The interrupt controller has the ability to control interrupts from 22 different FIQ and IRQ sources. The Interrupt controller has these features:

- Supports 22 interrupts from a variety of sources (such as UARTs, SSI1, and key matrix.)
- Routes interrupt sources to the ARM720T's IRQ or FIQ (Fast IRQ) inputs
- Five dedicated off-chip interrupt lines operate as level sensitive interrupts

Table 11 shows the interrupt controller pin assignments.

Table 11. Interrupt Controller Pin Assignments

Pin Mnemonic	I/O	Pin Description
nEINT[2:1]	I	External interrupt
EINT[3]	I	External interrupt
nEXTFIQ	I	External Fast Interrupt input
nMEDCHG/nBROM (Note)	I	Media change interrupt input

Note: Pins are multiplexed. See Table 19 on page 11 for more information.

Real-Time Clock

The EP7312 contains a 32-bit Real Time Clock (RTC) that can be written to and read from in the same manner as the timer counters. It also contains a 32-bit output match register which can be programmed to generate an interrupt.

- Driven by an external 32.768 kHz crystal oscillator

Table 12 shows the Real-Time Clock pin assignments.

Table 12. Real-Time Clock Pin Assignments

Pin Mnemonic	Pin Description
RTCCIN	Real-Time Clock Oscillator Input
RTCCOUT	Real-Time Clock Oscillator Output
VDDRTC	Real-Time Clock Oscillator Power
VSSRTC	Real-Time Clock Oscillator Ground

PLL and Clocking

The EP7312 processor and peripheral clocks have these features:

- Processor and peripheral clocks operate from a single 3.6864 MHz crystal or external 13 MHz clock
- Programmable clock speeds allow the peripheral bus to run at 18 MHz when the processor is set to 18 MHz and at 36 MHz when the processor is set to 36, 49 or 74 MHz, and at 45 MHz when the processor is set to 90 MHz.

Table 13 shows the PLL and clocking pin assignments.

Table 13. PLL and Clocking Pin Assignments

Pin Mnemonic	Pin Description
MOSCIN	Main Oscillator Input
MOSCOUT	Main Oscillator Output
VDDOSC	Main Oscillator Power
VSSOSC	Main Oscillator Ground

DC-to-DC Converter Interface (PWM)

- Provides two 96 kHz clock outputs with programmable duty ratio (from 1-in-16 to 15-in-16) that can be used to drive a positive or negative DC to DC converter

Table 14 shows the DC-to-DC Converter Interface pin assignments.

Table 14. DC-to-DC Converter Interface Pin Assignments

Pin Mnemonic	I/O	Pin Description
DRIVE[1:0]	I/O	PWM drive output
FB[1:0]	I	PWM feedback input

Timers

- Internal (RTC) timer
- Two internal 16-bit programmable hardware count-down timers

General Purpose Input/Output (GPIO)

- Three 8-bit and one 3-bit GPIO ports
- Supports scanning keyboard matrix

Table 15 shows the GPIO pin assignments.

Table 15. General Purpose Input/Output Pin Assignments

Pin Mnemonic	I/O	Pin Description
PA[7:0]	I	GPIO port A
PB[7:0]	I	GPIO port B
PD[0]/LEDFLSH (Note)	I/O	GPIO port D
PD[5:1]	I/O	GPIO port D
PD[7:6]/SDQM[1:0] (Note)	I/O	GPIO port D
PE[1:0]/BOOTSEL[1:0] (Note)	I	GPIO port E
PE[2]/CLKSEL (Note)	I	GPIO port E

Note: Pins are multiplexed. See Table 19 on page 11 for more information.

Hardware Debug Interface

- Full JTAG boundary scan and Embedded ICE[®] support

Table 16 shows the Hardware Debug Interface pin assignments.

Table 16. Hardware Debug Interface Pin Assignments

Pin Mnemonic	I/O	Pin Description
TCLK	I	JTAG clock
TDI	I	JTAG data input
TDO	O	JTAG data output
nTRST	I	JTAG async reset input
TMS	I	JTAG mode select

LED Flasher

A dedicated LED flasher module can be used to generate a low frequency signal on Port D pin 0 for the purpose of blinking an LED without CPU intervention. The LED flasher feature is ideal as a visual annunciator in battery powered applications, such as a voice mail indicator on a portable phone or an appointment reminder on a PDA. Table 17 shows the LED Flasher pin assignments.

- Software adjustable flash period and duty cycle
- Operates from 32 kHz RTC clock
- Will continue to flash in IDLE and STANDBY states
- 4 mA drive current

Table 17. LED Flasher Pin Assignments

Pin Mnemonic	I/O	Pin Description
PD[0]/LEDFLSH (Note)	O	LED flasher driver

Note: Pins are multiplexed. See Table 19 on page 11 for more information.

Internal Boot ROM

The internal 128-byte Boot ROM facilitates download of saved code to the on-board SRAM/FLASH.

Packaging

The EP7312 is available in a 208-pin LQFP package, 256-ball PBGA package, or a 204-ball TFBGA package.

Static Memory

Figure 7 through Figure 10 define the timings associated with all phases of the Static Memory. The following table contains the values for the timings of each of the Static Memory modes.

Parameter	Symbol	Min	Typ	Max	Unit
EXPCLK rising edge to nCS assert delay time	t_{CSd}	2	8	20	ns
EXPCLK falling edge to nCS deassert hold time	t_{CSh}	2	7	20	ns
EXPCLK rising edge to A assert delay time	t_{Ad}	4	9	16	ns
EXPCLK falling edge to A deassert hold time	t_{Ah}	3	10	19	ns
EXPCLK rising edge to nMWE assert delay time	t_{MWd}	3	6	10	ns
EXPCLK rising edge to nMWE deassert hold time	t_{MWh}	3	6	10	ns
EXPCLK falling edge to nMOE assert delay time	t_{MOEd}	3	7	10	ns
EXPCLK falling edge to nMOE deassert hold time	t_{MOEh}	2	7	10	ns
EXPCLK falling edge to HALFWORD deassert delay time	t_{HWd}	2	8	20	ns
EXPCLK falling edge to WORD assert delay time	t_{WDd}	2	8	16	ns
EXPCLK rising edge to data valid delay time	t_{Dv}	8	13	21	ns
EXPCLK falling edge to data invalid delay time	t_{Dnv}	6	15	30	ns
Data setup to EXPCLK falling edge time	t_{Ds}	-	-	1	ns
EXPCLK falling edge to data hold time	t_{Dh}	-	-	3	ns
EXPCLK rising edge to WRITE assert delay time	t_{WRd}	5	11	23	ns
EXPREADY setup to EXPCLK falling edge time	t_{EXs}	-	-	0	ns
EXPCLK falling edge to EXPREADY hold time	t_{EXh}	-	-	0	ns

Static Memory Single Read Cycle

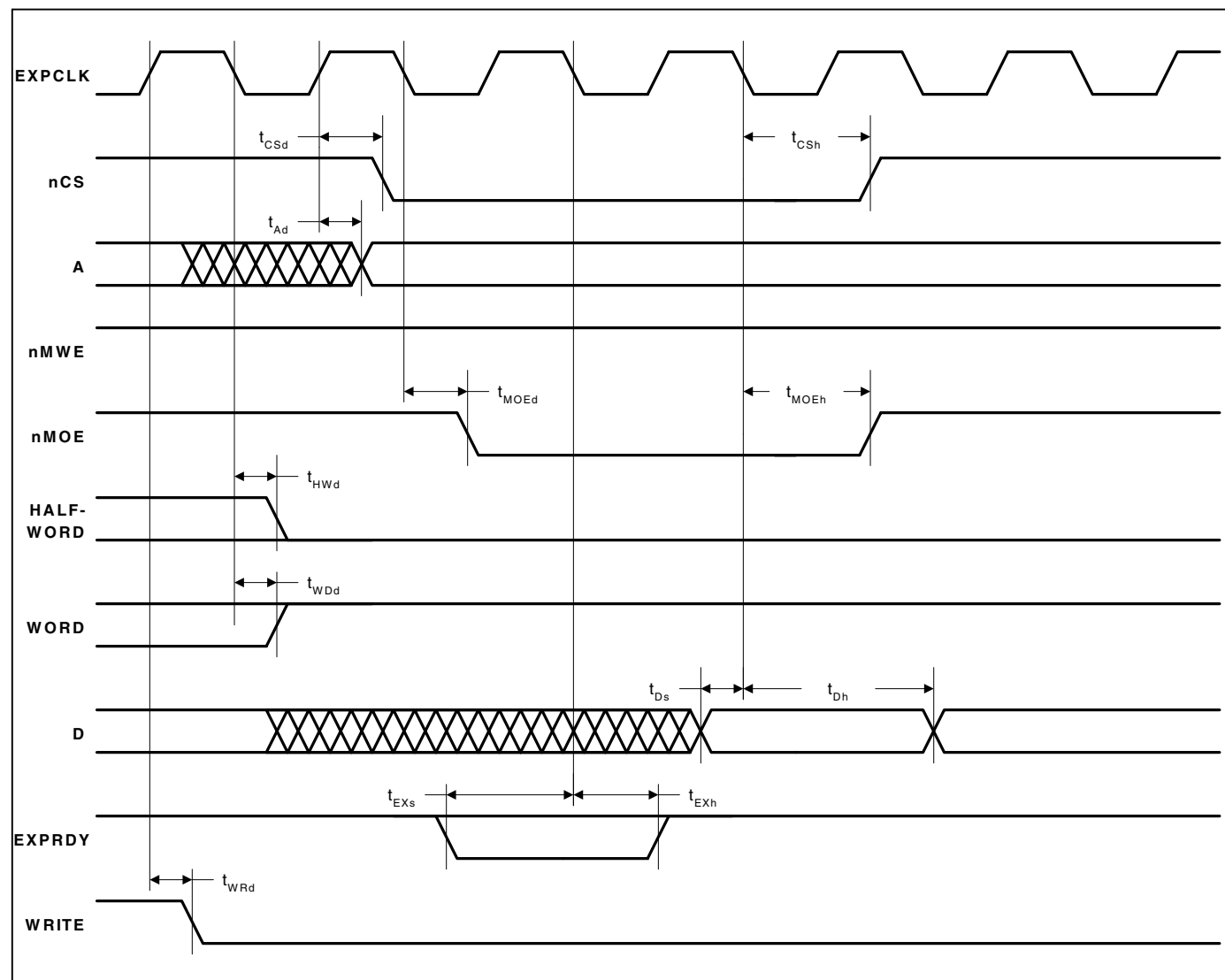


Figure 7. Static Memory Single Read Cycle Timing Measurement

Note: 1. The cycle time can be extended by integer multiples of the clock period (22 ns at 45 MHz, 27 ns at 36 MHz, 54 ns at 18.432 MHz, and 77 ns at 13 MHz), by either driving EXPRDY low and/or by programming a number of wait states. EXPRDY is sampled on the falling edge of EXPCLK before the data transfer. If low at this point, the transfer is delayed by one clock period where EXPRDY is sampled again. EXPCLK need not be referenced when driving EXPRDY, but is shown for clarity.
2. Address, Halfword, Word, and Write hold state until next cycle.

Static Memory Burst Read Cycle

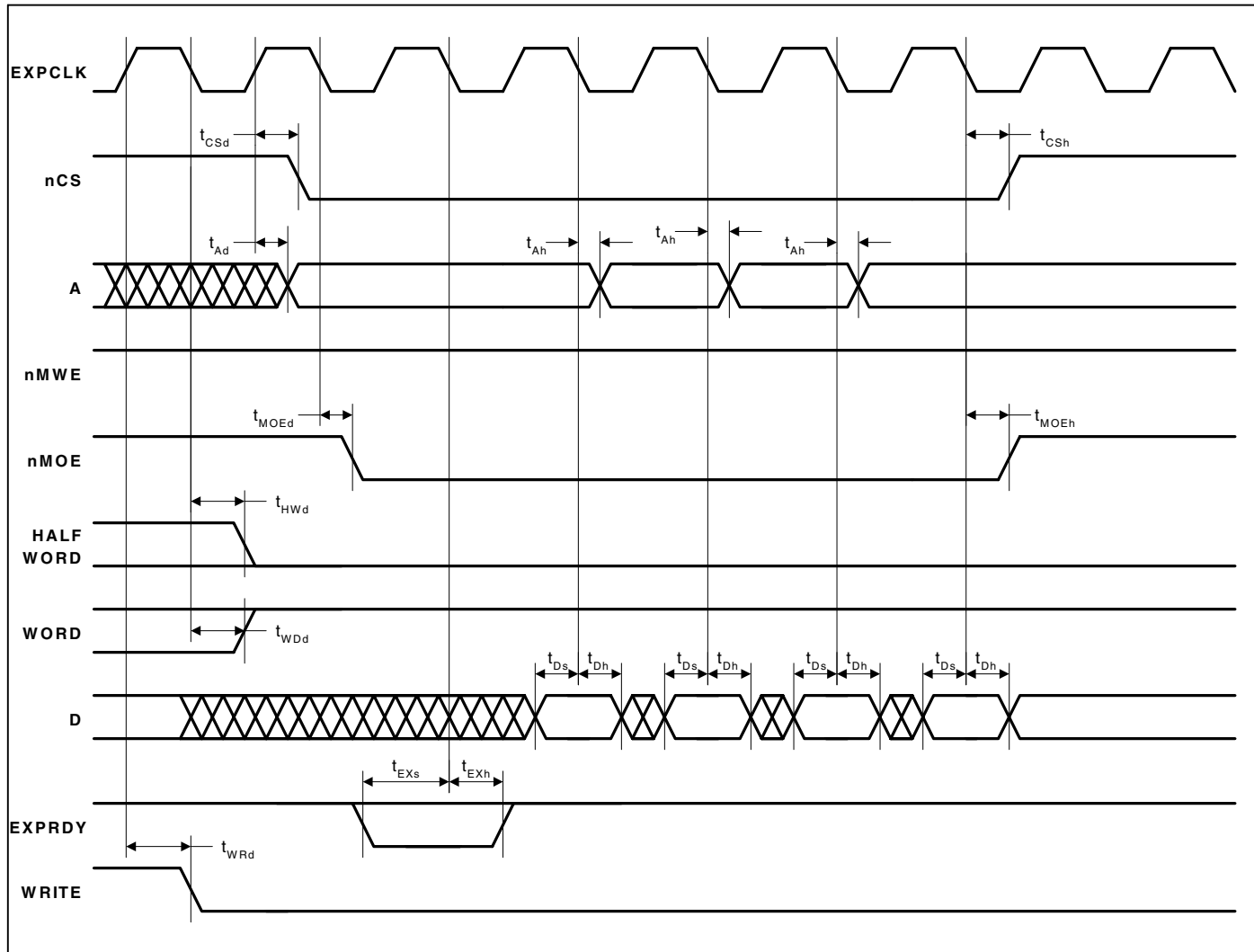


Figure 9. Static Memory Burst Read Cycle Timing Measurement

- Note:
1. Four cycles are shown in the above diagram (minimum wait states, 1-0-0-0). This is the maximum number of consecutive cycles that can be driven. The number of consecutive cycles can be programmed from 2 to 4, inclusively.
 2. The cycle time can be extended by integer multiples of the clock period (22 ns at 45 MHz, 27 ns at 36 MHz, 54 ns at 18.432 MHz, and 77 ns at 13 MHz), by either driving EXPRDY low and/or by programming a number of wait states. EXPRDY is sampled on the falling edge of EXPCLK before the data transfer. If low at this point, the transfer is delayed by one clock period where EXPRDY is sampled again. EXPCLK need not be referenced when driving EXPRDY, but is shown for clarity.
 3. Consecutive reads with sequential access enabled are identical except that the sequential access wait state field is used to determine the number of wait states, and no idle cycles are inserted between successive non-sequential ROM/expansion cycles. This improves performance so the SQAEN bit should always be set where possible.
 4. Address, Halfword, Word, and Write hold state until next cycle.

SSI2 Interface

Parameter	Symbol	Min	Max	Unit
SSICLK period (slave mode)	t_{clk_per}	185	2050	ns
SSICLK high time	t_{clk_high}	925	1025	ns
SSICLK low time	t_{clk_low}	925	1025	ns
SSICLK rise/fall time	t_{clkrf}	3	18	ns
SSICLK rising edge to RX and/or TX frame sync high time	t_{FRd}	-	3	ns
SSICLK rising edge to RX and/or TX frame sync low time	t_{FRa}	-	8	ns
SSIRXFR and/or SSITXFR period	t_{FR_per}	960	990	ns
SSIRXDA setup to SSICLK falling edge time	t_{RXs}	3	7	ns
SSIRXDA hold from SSICLK falling edge time	t_{RXh}	3	7	ns
SSICLK rising edge to SSITXDA data valid delay time	t_{TXd}	-	2	ns
SSITXDA valid time	t_{TXv}	960	990	ns

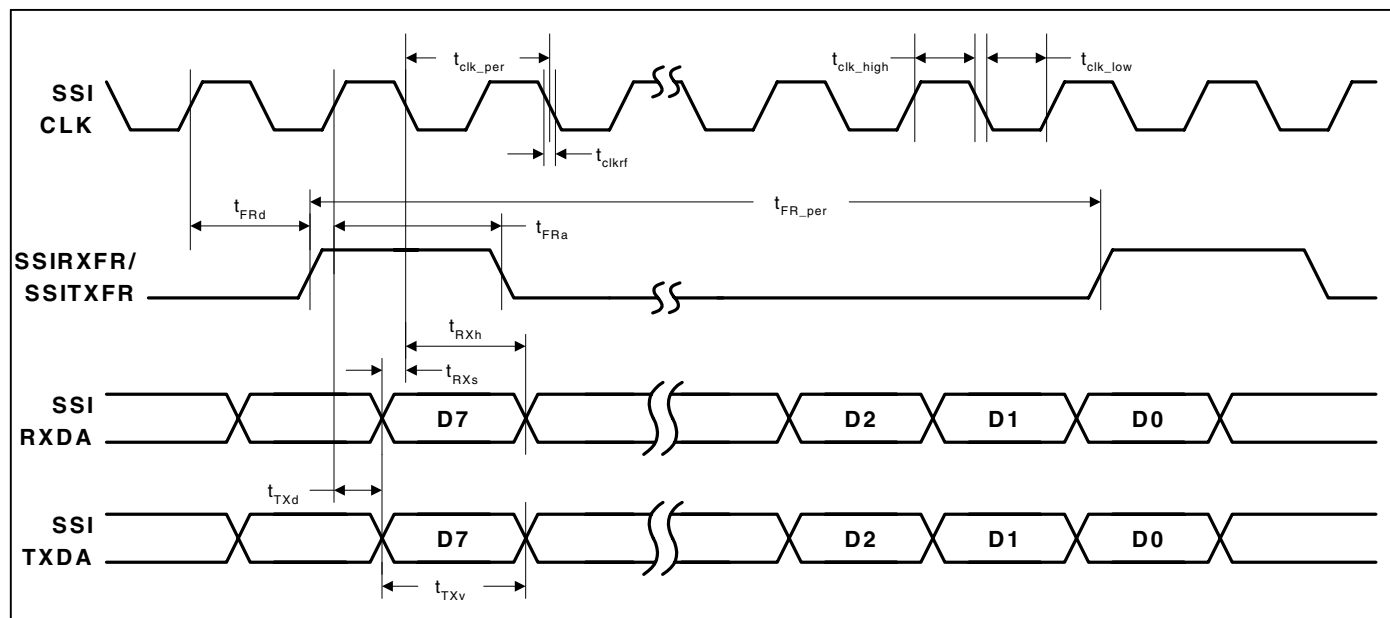


Figure 12. SSI2 Interface Timing Measurement

JTAG Interface

Parameter	Symbol	Min	Max	Units
TCK clock period	$t_{\text{clk_per}}$	2	-	ns
TCK clock high time	$t_{\text{clk_high}}$	1	-	ns
TCK clock low time	$t_{\text{clk_low}}$	1	-	ns
JTAG port setup time	$t_{\text{JP}s}$	-	0	ns
JTAG port hold time	$t_{\text{JP}h}$	-	3	ns
JTAG port clock to output	$t_{\text{JP}co}$	-	10	ns
JTAG port high impedance to valid output	$t_{\text{JP}zx}$	-	12	ns
JTAG port valid output to high impedance	$t_{\text{JP}xz}$	-	19	ns

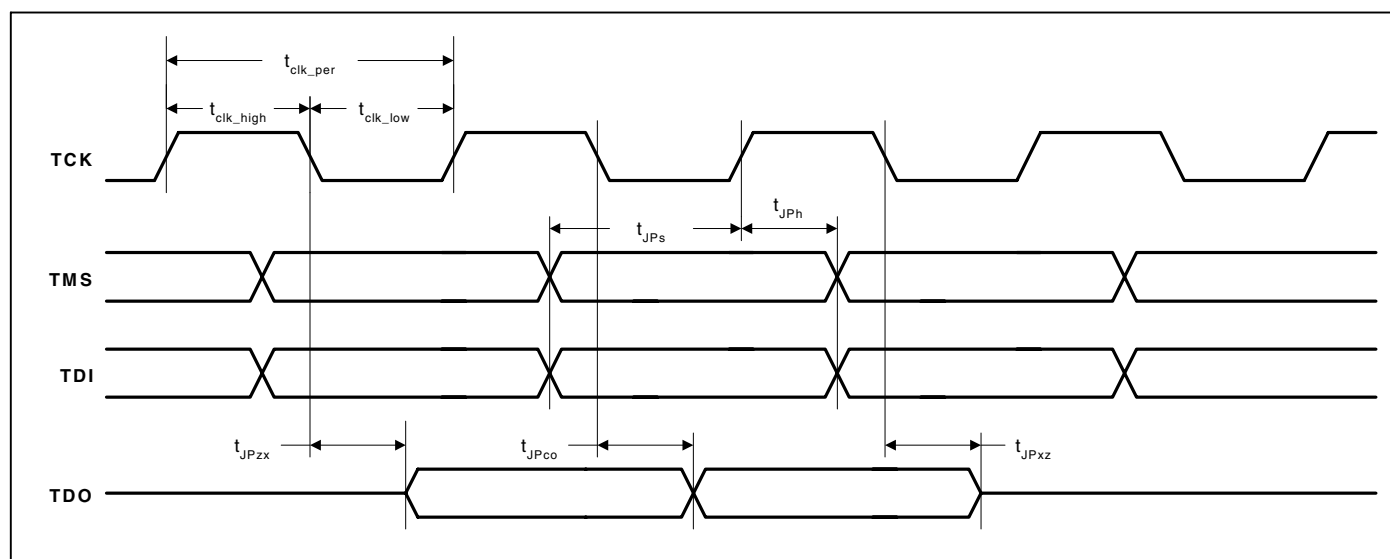


Figure 14. JTAG Timing Measurement

208-Pin LQFP Pin Diagram

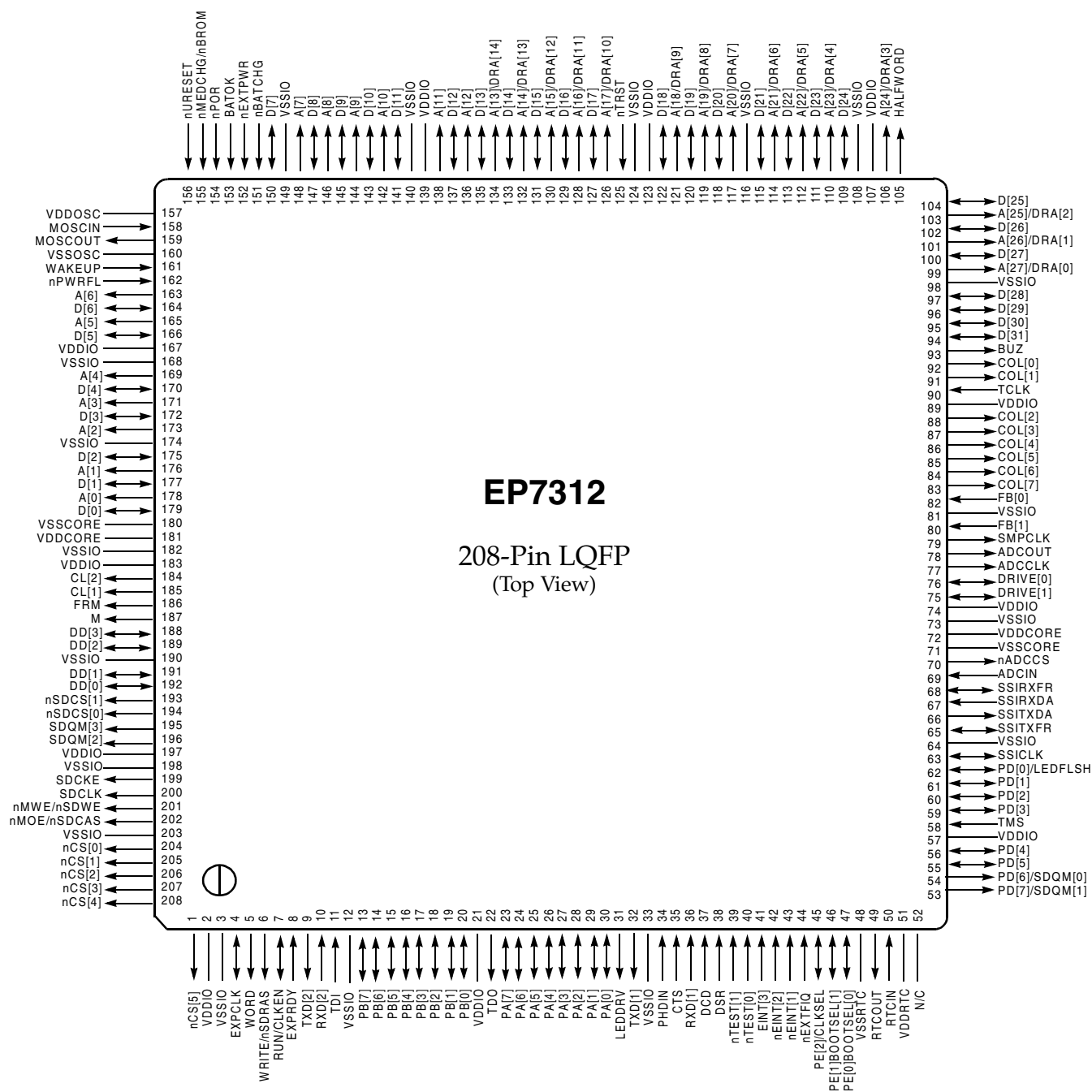


Figure 16. 208-Pin LQFP (Low Profile Quad Flat Pack) Pin Diagram

Note: 1. N/C should not be grounded but left as no connects.

208-Pin LQFP Numeric Pin Listing

Table 20. 208-Pin LQFP Numeric Pin Listing

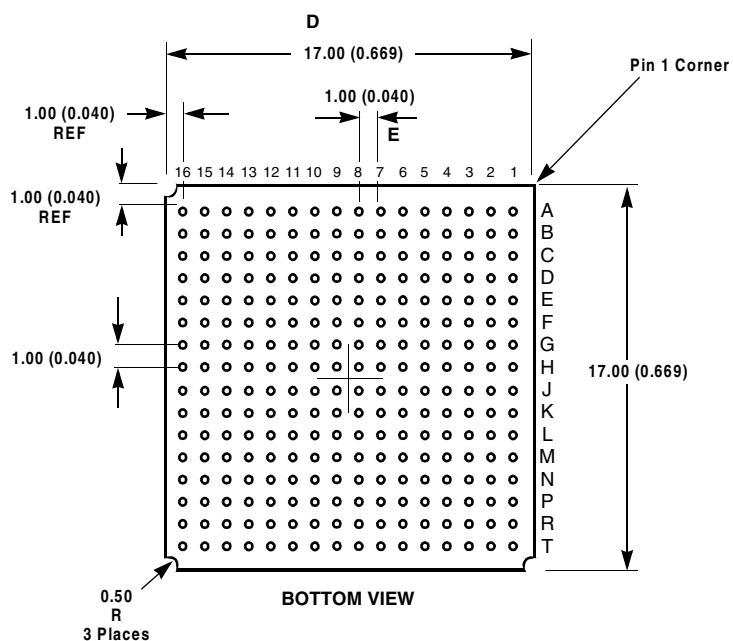
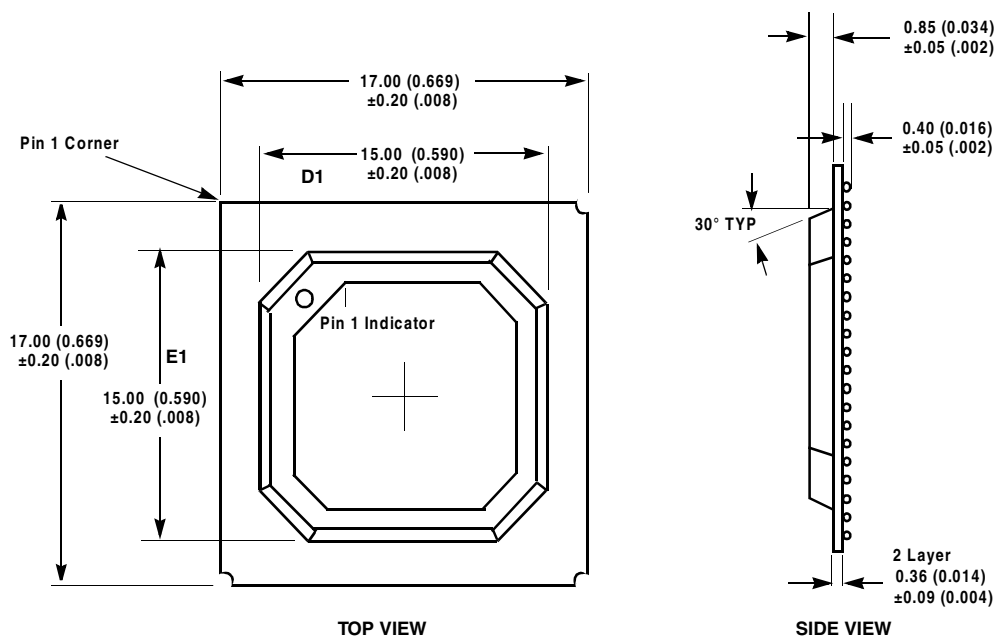
Pin No.	Signal	Strength [†]	Reset State	Type	Description
1	nCS[5]	1	Low	O	Chip select 5
2	VDDIO			Pad Pwr	Digital I/O power, 3.3 V
3	VSSIO			Pad Gnd	I/O ground
4	EXPCLK	1		I	Expansion clock input
5	WORD	1	Low	O	Word access select output
6	WRITE/nSDRAS	1	Low	O	Transfer direction / SDRAM RAS signal output
7	RUN/CLKEN	1	Low	O	Run output / clock enable output
8	EXPRDY	1		I	Expansion port ready input
9	TXD[2]	1	High	O	UART 2 transmit data output
10	RXD[2]			I	UART 2 receive data input
11	TDI	with p/u*		I	JTAG data input
12	VSSIO			Pad Gnd	I/O ground
13	PB[7]	1	Input [‡]	I/O	GPIO port B
14	PB[6]	1	Input [‡]	I/O	GPIO port B
15	PB[5]	1	Input [‡]	I/O	GPIO port B
16	PB[4]	1	Input [‡]	I/O	GPIO port B
17	PB[3]	1	Input [‡]	I/O	GPIO port B
18	PB[2]	1	Input [‡]	I/O	GPIO port B
19	PB[1]	1	Input [‡]	I/O	GPIO port B
20	PB[0]	1	Input [‡]	I/O	GPIO port B
21	VDDIO			Pad Pwr	Digital I/O power, 3.3 V
22	TDO	1	Input [‡]	O	JTAG data out
23	PA[7]	1	Input [‡]	I/O	GPIO port A
24	PA[6]	1	Input [‡]	I/O	GPIO port A
25	PA[5]	1	Input [‡]	I/O	GPIO port A
26	PA[4]	1	Input [‡]	I/O	GPIO port A
27	PA[3]	1	Input [‡]	I/O	GPIO port A
28	PA[2]	1	Input [‡]	I/O	GPIO port A
29	PA[1]	1	Input [‡]	I/O	GPIO port A
30	PA[0]	1	Input [‡]	I/O	GPIO port A
31	LEDDRV	1	Low	O	IR LED drive
32	TXD[1]	1	High	O	UART 1 transmit data out
33	VSSIO	1	High	Pad Gnd	I/O ground
34	PHDIN			I	Photodiode input
35	CTS			I	UART 1 clear to send input
36	RXD[1]			I	UART 1 receive data input
37	DCD			I	UART 1 data carrier detect

Table 20. 208-Pin LQFP Numeric Pin Listing (Continued)

Pin No.	Signal	Strength [†]	Reset State	Type	Description
118	D[20]	1	Low	I/O	Data I/O
119	A[19]/DRA[8]	1	Low	O	System byte address / SDRAM address
120	D[19]	1	Low	I/O	Data I/O
121	A[18]/DRA[9]	1	Low	O	System byte address / SDRAM address
122	D[18]	1	Low	I/O	Data I/O
123	VDDIO			Pad Pwr	Digital I/O power, 3.3 V
124	VSSIO			Pad Gnd	I/O ground
125	nTRST			I	JTAG async reset input
126	A[17]/DRA[10]	1	Low	O	System byte address / SDRAM address
127	D[17]	1	Low	I/O	Data I/O
128	A[16]/DRA[11]	1	Low	O	System byte address / SDRAM address
129	D[16]	1	Low	I/O	Data I/O
130	A[15]/DRA[12]	1	Low	O	System byte address / SDRAM address
131	D[15]	1	Low	I/O	Data I/O
132	A[14]/DRA[13]	1	Low	O	System byte address / SDRAM address
133	D[14]	1	Low	I/O	Data I/O
134	A[13]/DRA[14]	1	Low	O	System byte address / SDRAM address
135	D[13]	1	Low	I/O	Data I/O
136	A[12]	1	Low	O	System byte address
137	D[12]	1	Low	I/O	Data I/O
138	A[11]	1	Low	O	System byte address
139	VDDIO			Pad Pwr	Digital I/O power, 3.3 V
140	VSSIO			Pad Gnd	I/O ground
141	D[11]	1	Low	I/O	Data I/O
142	A[10]	1	Low	O	System byte address
143	D[10]	1	Low	I/O	Data I/O
144	A[9]	1	Low	O	System byte address
145	D[9]	1	Low	I/O	Data I/O
146	A[8]	1	Low	O	System byte address
147	D[8]	1	Low	I/O	Data I/O
148	A[7]	1	Low	O	System byte address
149	VSSIO			Pad Gnd	I/O ground
150	D[7]	1	Low	I/O	Data I/O
151	nBATCHG			I	Battery changed sense input
152	nEXTPWR			I	External power supply sense input
153	BATOK			I	Battery OK input
154	nPOR	Schmitt		I	Power-on reset input
155	nMEDCHG/nBROM			I	Media change interrupt input / internal ROM boot enable
156	nURESET	Schmitt		I	User reset input
157	VDDOSC			Oscillator Power	Oscillator power in, 2.5 V
158	MOSCIN			I	Main oscillator input
159	MOSCOUT			O	Main oscillator output
160	VSSOSC			Oscillator Ground	Oscillator Ground

Table 21. 204-Ball TFBGA Ball Listing (Continued)

Ball Location	Name	Strength [†]	Reset State	Type	Description
W11	ADCOUT	1	Low	O	SSI1 ADC serial data output
W12	FB[0]			I	PWM feedback input
W13	COL[5]	1	High	O	Keyboard scanner column drive
W14	COL[2]	1	High	O	Keyboard scanner column drive
W15	COL[0]	1	High	O	Keyboard scanner column drive
W16	D[30]	1	Low	I/O	Data I/O
W17	A[27]/DRA[0]	2	Low	O	System byte address / SDRAM address
W18	D[26]	1	Low	I/O	Data I/O
W19	VDDIO			Pad power	Digital I/O power, 3.3V
W20	D[25]	1	Low	I/O	Data I/O
Y1	VSSIO			Pad ground	I/O ground
Y2	VSSIO			Pad ground	I/O ground
Y3	VSSIO			Pad ground	I/O ground
Y4	PD[5]	1	Low	I/O	GPIO port D
Y5	PD[3]	1	Low	I/O	GPIO port D
Y6	PD[0]/LEDFLSH	1	Low	I/O	GPIO port D / LED blinker output
Y7	SSITXDA	1	Low	O	DAI/CODEC/SSI2 serial data output
Y8	ADCIN			I	SSI1 ADC serial input
Y9	VDDCORE			Core power	Digital core power, 2.5V
Y10	DRIVE[0]	2	Input [†]	I/O	PWM drive output
Y11	SMPCLK	1	Low	O	SSI1 ADC sample clock
Y12	FB[1]			I	PWM feedback input
Y13	COL[6]	1	High	O	Keyboard scanner column drive
Y14	COL[3]	1	High	O	Keyboard scanner column drive
Y15	COL[1]	1	High	O	Keyboard scanner column drive
Y16	D[31]	1	Low	I/O	Data I/O
Y17	D[28]	1	Low	I/O	Data I/O
Y18	D[27]	1	Low	I/O	Data I/O
Y19	A[25]/DRA[2]	2	Low	O	System byte address / SDRAM address



JEDEC #: MO-151
Ball Diameter: 0.50 mm $\pm$ 0.10 mm
17 $\times$ 17 $\times$ 1.61 mm body

256-Ball PBGA Pinout (Top View)

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	
A	VDDIO	nCS[4]	nCS[1]	SDCLK	SDQM[3]	DD[1]	M	VDDIO	D[0]	D[2]	A[3]	VDDIO	A[6]	MOSCOUT	VDDOSC	VSSIO	A
B	nCS[5]	VDDIO	nCS[3]	nMOE/ nSDCAS	VDDIO	nSDCS[1]	DD[2]	CL[1]	VDDCORE	D[1]	A[2]	A[4]	A[5]	WAKEUP	VDDIO	nURESET	B
C	VDDIO	EXPCLK	VSSIO	VDDIO	VSSIO	VSSIO	VSSIO	VDDIO	VSSIO	VSSIO	VSSIO	VDDIO	VSSIO	VSSIO	nPOR	nEXTPWR	C
D	WRITE/ nSDRAS	EXPDIY	VSSIO	VDDIO	nCS[2]	nMWE/ nSDWE	nSDCS[0]	CL[2]	VSSRTC	D[4]	nPWRFL	MOSCIN	VDDIO	VSSIO	D[7]	D[8]	D
E	RXD[2]	PB[7]	TDI	WORD	VSSIO	nCS[0]	SDQM[2]	FRM	A[0]	D[5]	VSSOSC	VSSIO	nMEDCHG/ nBROM	VDDIO	D[9]	D[10]	E
F	PB[5]	PB[3]	VSSIO	TXD[2]	RUN/ CLKEN	VSSIO	SDCKE	DD[3]	A[1]	D[6]	VSSRTC	BATOK	nBATCHG	VSSIO	D[11]	VDDIO	F
G	PB[1]	VDDIO	TDO	PB[4]	PB[6]	VSSCore	VSSRTC	DD[0]	D[3]	VSSRTC	A[7]	A[8]	A[9]	VSSIO	D[12]	D[13]	G
H	PA[7]	PA[5]	VSSIO	PA[4]	PA[6]	PB[0]	PB[2]	VSSRTC	VSSRTC	A[10]	A[11]	A[12]	A[13]/ DRA[14]	VSSIO	D[14]	D[15]	H
J	PA[3]	PA[1]	VSSIO	PA[2]	PA[0]	TXD[1]	CTS	VSSRTC	VSSRTC	A[17]/ DRA[10]	A[16]/ DRA[11]	A[15]/ DRA[12]	A[14]/ DRA[13]	nTRST	D[16]	D[17]	J
K	LEDDRV	PHDIN	VSSIO	DCD	nTEST[1]	EINT[3]	VSSRTC	ADCIN	COL[4]	TCLK	D[20]	D[19]	D[18]	VSSIO	VDDIO	VDDIO	K
L	RXD[1]	DSR	VDDIO	nEINT[1]	PE[2]/ CLKSEL	VSSRTC	PD[0]/ LEDFLSH	VSSRTC	COL[6]	D[31]	VSSRTC	A[22]/ DRA[5]	A[21]/ DRA[6]	VSSIO	A[18]/ DRA[9]	A[19]/ DRA[8]	L
M	nTEST[0]	nEINT[2]	VDDIO	PE[0]/ BOOTSEL[0]	TMS	VDDIO	SSITXFR	DRIVE[1]	FB[0]	COL[0]	D[27]	VSSIO	A[23]/ DRA[4]	VDDIO	A[20]/ DRA[7]	D[21]	M
N	nEXTFIQ	PE[1]/ BOOTSEL[1]	VSSIO	VDDIO	PD[5]	PD[2]	SSIRXDA	ADCCLK	SMPCLK	COL[2]	D[29]	D[26]	HALFWORD	VSSIO	D[22]	D[23]	N
P	VSSRTC	RTCOUT	VSSIO	VSSIO	VDDIO	VSSIO	VSSIO	VDDIO	VSSIO	VDDIO	VSSIO	VSSIO	VDDIO	VSSIO	D[24]	VDDIO	P
R	RTCIN	VDDIO	PD[4]	PD[1]	SSITXDA	nADCCS	VDDIO	ADCOUT	COL[7]	COL[3]	COL[1]	D[30]	A[27]/ DRA[0]	A[25]/ DRA[2]	VDDIO	A[24]/ DRA[3]	R
T	VDDRTC	PD[7]/ SDQM[1]	PD[6]/ SDQM[0]	PD[3]	SSICLK	SSIRXFR	VDDCORE	DRIVE[0]	FB[1]	COL[5]	VDDIO	BUZ	D[28]	A[26]/ DRA[1]	D[25]	VSSIO	T

Table 22. 256-Ball PBGA Ball Listing (Continued)

Ball Location	Name	Strength [†]	Reset State	Type	Description
C13	VSSIO			Pad ground	I/O ground
C14	VSSIO			Pad ground	I/O ground
C15	nPOR	Schmitt		I	Power-on reset input
C16	nEXTPWR			I	External power supply sense input
D1	WRITE/nSDRAS	1	Low	O	Transfer direction / SDRAM RAS signal output
D2	EXPRDY	1		I	Expansion port ready input
D3	VSSIO			Pad ground	I/O ground
D4	VDDIO			Pad power	Digital I/O power, 3.3V
D5	nCS[2]	1	High	O	Chip select 2
D6	nMWE/nSDWE	1	High	O	ROM, expansion write enable/ SDRAM write enable control signal
D7	nSDCS[0]	1	High	O	SDRAM chip select 2
D8	CL[2]	1	Low	O	LCD pixel clock out
D9	VSSRTC			Core ground	Real time clock ground
D10	D[4]	1	Low	I/O	Data I/O
D11	nPWRFL			I	Power fail sense input
D12	MOSCIN			I	Main oscillator input
D13	VDDIO			Pad power	Digital I/O power, 3.3V
D14	VSSIO			Pad ground	I/O ground
D15	D[7]	1	Low	I/O	Data I/O
D16	D[8]	1	Low	I/O	Data I/O
E1	RXD[2]			I	UART 2 receive data input
E2	PB[7]	1	Input [†]	I	GPIO port B
E3	TDI	with p/u*		I	JTAG data input
E4	WORD	1	Low	O	Word access select output
E5	VSSIO			Pad ground	I/O ground
E6	nCS[0]	1	High	O	Chip select 0
E7	SDQM[2]	2	Low	O	SDRAM byte lane mask
E8	FRM	1	Low	O	LCD frame synchronization pulse
E9	A[0]	2	Low	O	System byte address
E10	D[5]	1	Low	I/O	Data I/O
E11	VSSOSC			Oscillator ground	PLL ground
E12	VSSIO			Pad ground	I/O ground
E13	nMEDCHG/nBROM			I	Media change interrupt input / internal ROM boot enable
E14	VDDIO			Pad power	Digital I/O power, 3.3V
E15	D[9]	1	Low	I/O	Data I/O
E16	D[10]	1	Low	I/O	Data I/O
F1	PB[5]	1	Input [†]	I	GPIO port B
F2	PB[3]	1	Input [†]	I	GPIO port B
F3	VSSIO			Pad ground	I/O ground
F4	TXD[2]	1	High	O	UART 2 transmit data output
F5	RUN/CLKEN	1	Low	O	Run output / clock enable output
F6	VSSIO			Pad ground	I/O ground
F7	SDCKE	2	Low	O	SDRAM clock enable output
F8	DD[3]	1	Low	O	LCD serial display data
F9	A[1]	2	Low	O	System byte address

Table 22. 256-Ball PBGA Ball Listing (Continued)

Ball Location	Name	Strength [†]	Reset State	Type	Description
J5	PA[0]	1	Input [†]	I/O	GPIO port A
J6	TXD[1]	1	High	O	UART 1 transmit data out
J7	CTS			I	UART 1 clear to send input
J8	VSSRTC			RTC ground	Real time clock ground
J9	VSSRTC			RTC ground	Real time clock ground
J10	A[17]/DRA[10]	1	Low	O	System byte address / SDRAM address
J11	A[16]/DRA[11]	1	Low	O	System byte address / SDRAM address
J12	A[15]/DRA[12]	1	Low	O	System byte address / SDRAM address
J13	A[14]/DRA[13]	1	Low	O	System byte address / SDRAM address
J14	nTRST			I	JTAG async reset input
J15	D[16]	1	Low	I/O	Data I/O
J16	D[17]	1	Low	I/O	Data I/O
K1	LEDDRV	1	Low	O	IR LED drive
K2	PHDIN			I	Photodiode input
K3	VSSIO			Pad ground	I/O ground
K4	DCD			I	UART 1 data carrier detect
K5	nTEST[1]	With p/u*		I	Test mode select input
K6	EINT[3]			I	External interrupt
K7	VSSRTC			RTC ground	Real time clock ground
K8	ADCIN			I	SSI1 ADC serial input
K9	COL[4]	1	High	O	Keyboard scanner column drive
K10	TCLK			I	JTAG clock
K11	D[20]	1	Low	I/O	Data I/O
K12	D[19]	1	Low	I/O	Data I/O
K13	D[18]	1	Low	I/O	Data I/O
K14	VSSIO			Pad ground	I/O ground
K15	VDDIO			Pad power	Digital I/O power, 3.3V
K16	VDDIO			Pad power	Digital I/O power, 3.3V
L1	RXD[1]			I	UART 1 receive data input
L2	DSR			I	UART 1 data set ready input
L3	VDDIO			Pad power	Digital I/O power, 3.3V
L4	nEINT[1]			I	External interrupt input
L5	PE[2]/CLKSEL	1	Input [†]	I/O	GPIO port E / clock input mode select
L6	VSSRTC			RTC ground	Real time clock ground
L7	PD[0]/LEDFLSH	1	Low	I/O	GPIO port D / LED blinker output
L8	VSSRTC			Core ground	Real time clock ground
L9	COL[6]	1	High	O	Keyboard scanner column drive
L10	D[31]	1	Low	I/O	Data I/O
L11	VSSRTC			RTC ground	Real time clock ground
L12	A[22]/DRA[5]	1	Low	O	System byte address / SDRAM address
L13	A[21]/DRA[6]	1	Low	O	System byte address / SDRAM address
L14	VSSIO			Pad ground	I/O ground
L15	A[18]/DRA[9]	1	Low	O	System byte address / SDRAM address
L16	A[19]/DRA[8]	1	Low	O	System byte address / SDRAM address
M1	nTEST[0]	With p/u*		I	Test mode select input
M2	nEINT[2]			I	External interrupt input
M3	VDDIO			Pad power	Digital I/O power, 3.3V

Table 23. JTAG Boundary Scan Signal Ordering (Continued)

LQFP Pin No.	TFBGA Ball	PBGA Ball	Signal	Type	Position
55	Y4	N5	PD[5]	I/O	95
56	V5	R3	PD[4]	I/O	98
59	Y5	T4	PD[3]	I/O	101
60	V6	N6	PD[2]	I/O	104
61	W6	R4	PD[1]	I/O	107
62	Y6	L7	PD[0]/LEDFLSH	O	110
68	W8	T6	SSIRXFR	I/O	122
69	Y8	K8	ADCIN	I	125
70	V9	R6	nADCCS	O	126
75	W10	M8	DRIVE1	I/O	128
76	Y10	T8	DRIVE0	I/O	131
77	V11	N8	ADCCLK	O	134
78	W11	R8	ADCOUT	O	136
79	Y11	N9	SMPCLK	O	138
80	Y12	T9	FB1	I	140
82	Y11	M9	FB0	I	141
83	Y12	R9	COL7	O	142
84	Y13	L9	COL6	O	144
85	W13	T10	COL5	O	146
86	V13	K9	COL4	O	148
87	Y14	R10	COL3	O	150
88	W14	N10	COL2	O	152
91	Y15	R11	COL1	O	154
92	W15	M10	COL0	O	156
93	V15	T12	BUZ	O	158
94	Y16	L10	D[31]	I/O	160
95	W16	R12	D[30]	I/O	163
96	V16	N11	D[29]	I/O	166
97	Y17	T13	D[28]	I/O	169
99	Y16	R13	A[27]/DRA[0]	Out	172
100	Y18	M11	D[27]	I/O	174
101	V17	T14	A[26]/DRA[1]	O	177
102	W18	N12	D[26]	I/O	179
103	Y19	R14	A[25]/DRA[2]	O	182
104	Y20	T15	D[25]	I/O	184
105	U18	N13	HALFWORD	O	187
106	V209	R16	A[24]/DRA[3]	O	189
109	U19	P15	D[24]	I/O	191

Table 23. JTAG Boundary Scan Signal Ordering (Continued)

LQFP Pin No.	TFBGA Ball	PBGA Ball	Signal	Type	Position
110	U20	M13	A[23]/DRA[4]	O	194
111	T19	N16	D[23]	I/O	196
112	T20	L12	A[22]/DRA[5]	O	199
113	R19	N15	D[22]	I/O	201
114	R20	L13	A[21]/DRA[6]	O	204
115	T18	M16	D[21]	I/O	206
117	P19	M15	A[20]/DRA[7]	O	209
118	P20	K11	D[20]	I/O	211
119	R18	L16	A[19]/DRA[8]	O	214
120	N19	K12	D[19]	I/O	216
121	N20	L15	A[18]/DRA[9]	O	219
122	P18	K13	D[18]	I/O	221
126	M19	J10	A[17]/DRA[10]	O	224
127	N18	J16	D[17]	I/O	226
128	L20	J11	A[16]/DRA[11]	O	229
129	L19	J15	D[16]	I/O	231
130	M18	J12	A[15]/DRA[12]	O	234
131	K20	H16	D[15]	I/O	236
132	K19	J13	A[14]/DRA[13]	O	239
133	K18	H15	D[14]	I/O	241
134	J20	H13	A[13]/DRA[14]	O	244
135	J19	G16	D[13]	I/O	246
136	H20	H12	A[12]	O	249
137	H19	G15	D[12]	I/O	251
138	J18	H11	A[11]	O	254
141	G20	F15	D[11]	I/O	256
142	H18	H10	A[10]	O	259
143	F20	E16	D[10]	I/O	261
144	G19	G13	A[9]	O	264
145	E20	E15	D[9]	I/O	266
146	F19	G12	A[8]	O	269
147	G18	D16	D[8]	I/O	271
148	D20	G11	A[7]	O	274
150	F18	D15	D[7]	I/O	276
151	D19	F13	nBATCHG	I	279
152	E19	C16	nEXTPWR	I	280
153	C19	F12	BATOK	I	281
154	C20	C15	nPOR	I	282

CONVENTIONS

This section presents acronyms, abbreviations, units of measurement, and conventions used in this data sheet.

Acronyms and Abbreviations

Table 24 lists abbreviations and acronyms used in this data sheet.

Table 24. Acronyms and Abbreviations

Acronym/ Abbreviation	Definition
A/D	analog-to-digital
ADC	analog-to-digital converter
CODEC	coder / decoder
D/A	digital-to-analog
DMA	direct-memory access
EPB	embedded peripheral bus
FCS	frame check sequence
FIFO	first in / first out
FIQ	fast interrupt request
GPIO	general purpose I/O
ICT	in circuit test
IR	infrared
IRQ	standard interrupt request
IrDA	Infrared Data Association
JTAG	Joint Test Action Group
LCD	liquid crystal display
LED	light-emitting diode
LQFP	low profile quad flat pack
LSB	least significant bit
MIPS	millions of instructions per second
MMU	memory management unit
MSB	most significant bit
PBGA	plastic ball grid array
PCB	printed circuit board
PDA	personal digital assistant
PLL	phase locked loop
p/u	pull-up resistor
RISC	reduced instruction set computer
RTC	Real-Time Clock
SIR	slow (9600–115.2 kbps) infrared
SRAM	static random access memory
SSI	synchronous serial interface

Table 24. Acronyms and Abbreviations (Continued)

Acronym/ Abbreviation	Definition
TAP	test access port
TLB	translation lookaside buffer
UART	universal asynchronous receiver

Units of Measurement

Table 25. Unit of Measurement

Symbol	Unit of Measure
°C	degree Celsius
fs	sample frequency
Hz	hertz (cycle per second)
kbps	kilobits per second
KB	kilobyte (1,024 bytes)
kHz	kilohertz
kΩ	kilo Ohm
Mbps	megabits (1,048,576 bits) per second
MB	megabyte (1,048,576 bytes)
MBps	megabytes per second
MHz	megahertz (1,000 kilohertz)
μA	microampere
μF	microfarad
μW	microwatt
μs	microsecond (1,000 nanoseconds)
mA	milliampere
mW	milliwatt
ms	millisecond (1,000 microseconds)
ns	nanosecond
V	volt
W	watt